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SHEET 1 OF 1

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  (PTO-1449)				ATTY. DOCKET NO. <b>50395-121</b>		SERIAL NO.	
				APPLICANT <b>Akihiro HACHIGO, et al.</b>			
				FILING DATE <b>April 04, 2002</b>		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
<i>ja</i>	5,160,869	11/03/92	Nakahata, et al	310	313A		
<i>ja</i>	5,446,329	08/29/95	Nakahata, et al	310	313A		
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
<i>ja</i>	3-198412	08/29/91	JAPAN (w/English Abstract)	H03H	9/145		
<i>ja</i>	5-83078	04/02/93	JAPAN (w/English Abstract)	H03H	9/145		
<i>ja</i>	64-62911	03/09/89	JAPAN (w/English Abstract)	H03H	9/25		
<i>ja</i>	9-51248	02/18/97	JAPAN (w/English Abstract)	H03H	9/25		
<i>ja</i>	10-276061	10/13/98	JAPAN (w/English Abstract)	H03H	9/25		
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
<i>ja</i>	Yamanouchi, et al "SAW PROPAGATION CHARACTERISTICS AND FABRICATION TECHNOLOGY OF PIEZOELECTRIC THIN FILM/DIAMOND STRUCTURE" 1989, IEEE, UltraSonics Symposium, Vol. 1, pages 351 - 354.						
<i>ja</i>	Shikata, et al "1.5GHZ SAW BANDPASS FILTER USING POLY-CRYSTALLINE DIAMOND" 1993, UltraSonics Symposium, pages 277-280						
<i>ja</i>	Nakahata, et al "HIGH FREQUENCY SURFACE ACOUSTIC WAVE FILTER USING ZnO/DIAMOND/Si STRUCTURE" 1992, UltraSonics Symposium, pages 377 - 380						
<i>ja</i>	Nakahata, et al "SAW DEVICES ON DIAMOND" 1995, IEEE UltraSonics Symposium, pages 361 - 370						
<i>ja</i>	Nakahata, et al "HIGH FREQUENCY SURFACE ACOUSTIC WAVE FILTER USING ZnO/DIAMOND/SI STRUCTURE" Reprinted from Jpn. J. Appl. Phys. Vol. 33, Part 1, No. 1A, January 1994						
EXAMINER <i>R. J. Quinn</i>				DATE CONSIDERED 12/22/04			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

